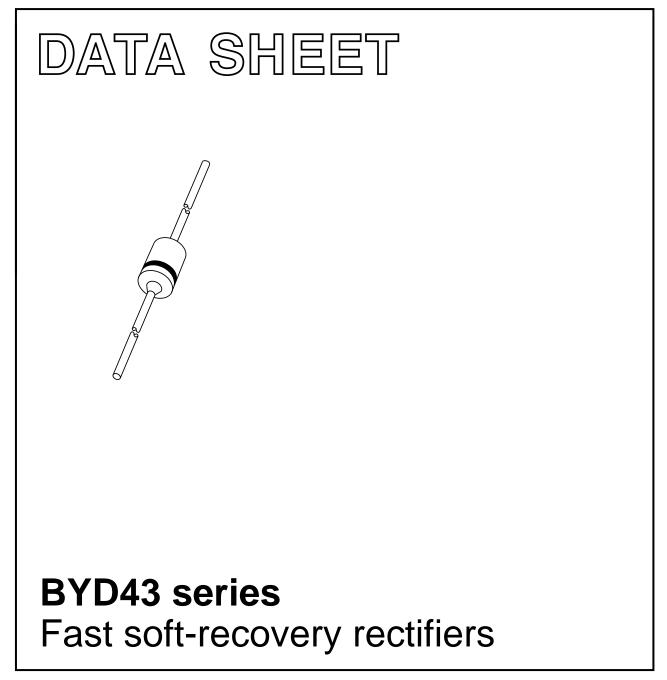
# DISCRETE SEMICONDUCTORS



Product specification Supersedes data of February 1995 File under Discrete Semiconductors, SC01 1996 Jun 05



## **BYD43 series**

#### FEATURES

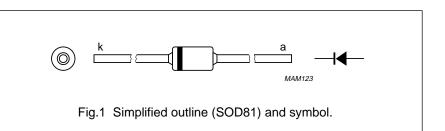
- · Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Available in ammo-pack.

#### DESCRIPTION

Cavity free cylindrical glass package through Implotec<sup>TM(1)</sup> technology. This package is hermetically sealed

and fatigue free as coefficients of expansion of all used parts are matched.

(1) Implotec is a trademark of Philips.



#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RSM</sub>	non-repetitive peak reverse voltage				
	BYD43U		_	1300	V
	BYD43V		_	1500	V
	BYD43-16		_	1700	V
	BYD43-18		_	1900	V
	BYD43-20		_	2100	V
V <sub>RRM</sub>	repetitive peak reverse voltage				
	BYD43U		_	1200	V
	BYD43V		_	1400	V
	BYD43-16		-	1600	V
	BYD43-18		_	1800	V
	BYD43-20		_	2000	V
I <sub>F(AV)</sub>	average forward current	$T_{tp} = 55 \ ^{\circ}C;$ lead length = 10 mm;			
	BYD43U and V	see Figs 2 and 3;	-	1.20	A
	BYD43-16 to 20	averaged over any 20 ms period; see also Figs 10 and 11	_	0.68	А
I <sub>F(AV)</sub>	average forward current	T <sub>amb</sub> = 65 °C; PCB mounting (see			
	BYD43U and V	Fig.20); see Figs 4 and 5;	-	0.65	A
	BYD43-16 to 20	averaged over any 20 ms period; see also Figs 10 and 11	_	0.30	А
I <sub>FRM</sub>	repetitive peak forward current	$T_{tp}$ = 55 °C; see Figs 6 and 7			
	BYD43U and V		-	11	A
	BYD43-16 to 20		_	6	A
I <sub>FRM</sub>	repetitive peak forward current	$T_{amb} = 65 \ ^{\circ}C$ ; see Figs 8 and 9			
	BYD43U and V		_	6.0	A
	BYD43-16 to 20		-	3.2	A

## **BYD43** series

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>FSM</sub>	non-repetitive peak forward current	t = 10 ms half sinewave; $T_j = T_{j max}$			
	BYD43U and V	prior to surge; $V_R = V_{RRMmax}$	_	6	A
	BYD43-16 to 20		_	6	A
T <sub>stg</sub>	storage temperature		-65	+175	°C
Tj	junction temperature	see Figs 12 and 13	-65	+175	°C

#### **ELECTRICAL CHARACTERISTICS**

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	$I_{F} = 1 \text{ A}; T_{j} = T_{j \max};$				
	BYD43U and V	see Figs 14 and 15	_	_	1.20	V
	BYD43-16 to 20		_	_	2.05	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 1 A;				
	BYD43U and V	see Figs 14 and 15	_	_	1.5	V
	BYD43-16 to 20		_	_	2.4	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = V <sub>RRMmax</sub> ;				
	BYD43U and V	see Figs 16 and 17	_	_	1	μA
	BYD43-16 to 20		_	_	5	μA
I <sub>R</sub>	reverse current	V <sub>R</sub> = V <sub>RRMmax</sub>				
	BYD43U and V	T <sub>j</sub> = 165 °C; see Fig 16	-	-	100	μA
	BYD43-16 to 20	T <sub>j</sub> = 125 °C; see Fig 17	_	_	50	μA
t <sub>rr</sub>	reverse recovery time	when switched from				
	BYD43U and V	$I_F = 0.5 \text{ A to } I_R = 1 \text{ A};$	_	_	250	ns
	BYD43-16 to 20	measured at $I_R = 0.25 A$ ; see Fig 22	_	_	300	ns
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 0 V;				
	BYD43U and V	see Figs 18 and 19	_	20	_	pF
	BYD43-16 to 20		_	15	-	pF
dI <sub>R</sub>	maximum slope of reverse recovery	when switched from				
dt	current	$I_F = 1 \text{ A to } V_R \ge 30 \text{ V}$				
	BYD43U and V	and dI <sub>F</sub> /dt = $-1 \text{ A/}\mu\text{s}$ ;	_	_	5	A/μs
	BYD43-16 to 20	see Fig.21	_	_	5	A/μs

#### THERMAL CHARACTERISTICS

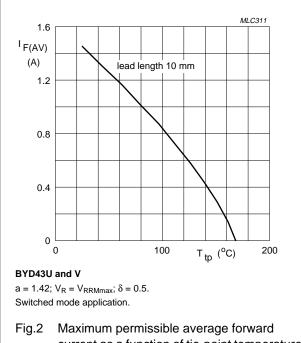
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length = 10 mm	60	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	120	K/W

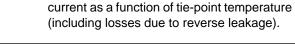
Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.20. For more information please refer to the *'General Part of Handbook SC01'*.

#### **BYD43** series

#### **GRAPHICAL DATA**





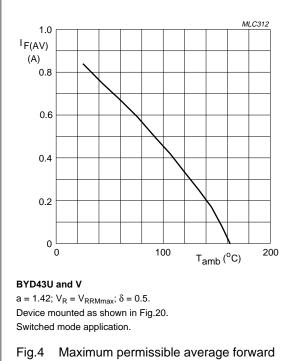


Fig.4 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).

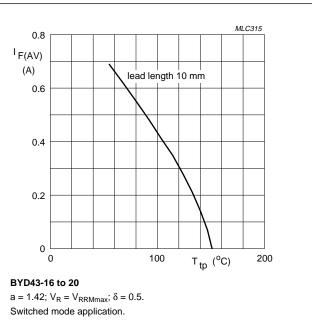


Fig.3 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).

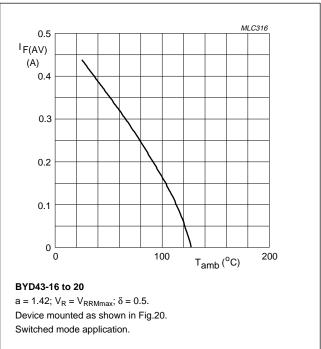
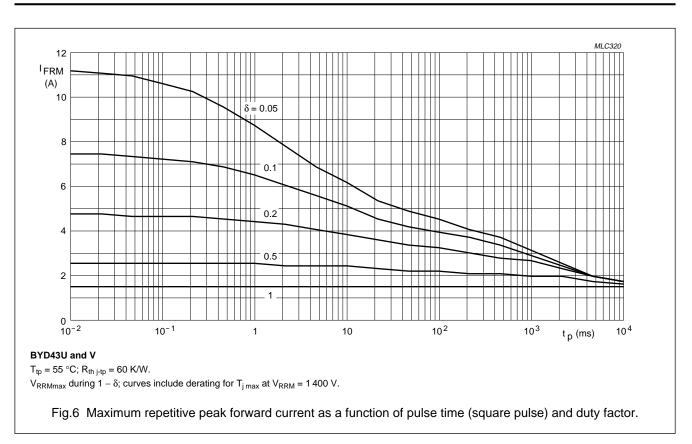
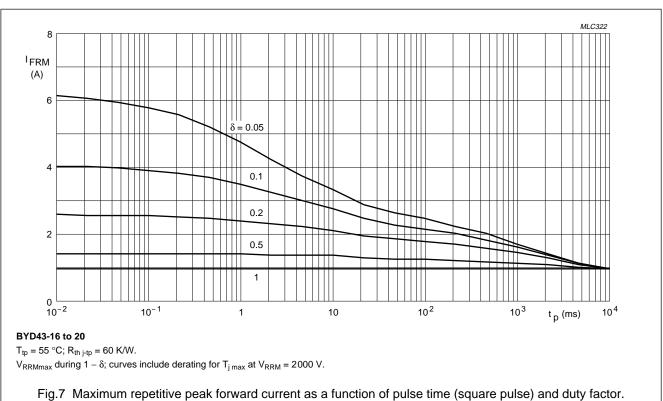
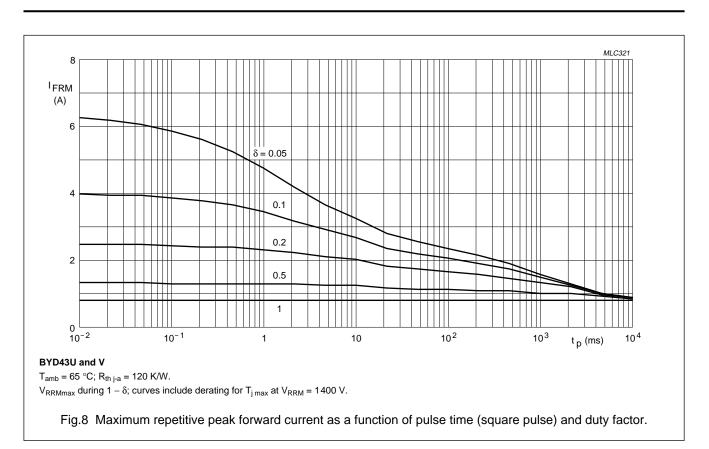


Fig.5 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).





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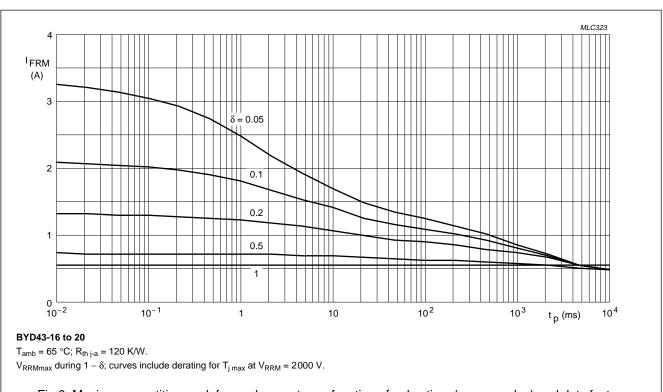
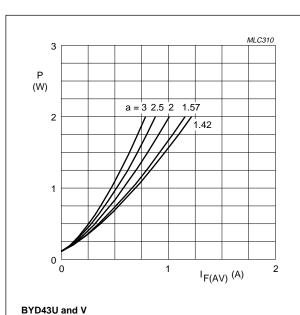


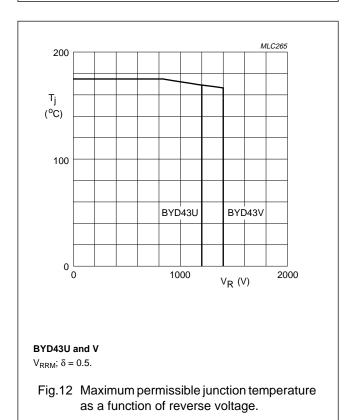
Fig.9 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

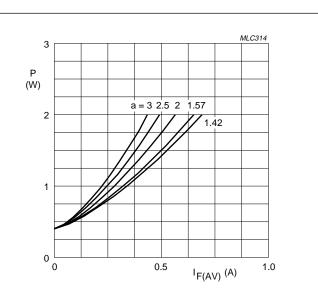
## **BYD43** series



 $a = I_{F(RMS)}/I_{F(AV)}; V_R = V_{RRMmax}; \delta = 0.5.$ 

Fig.10 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

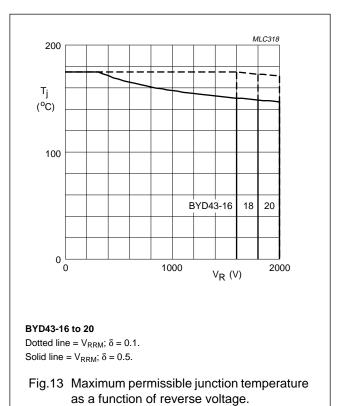


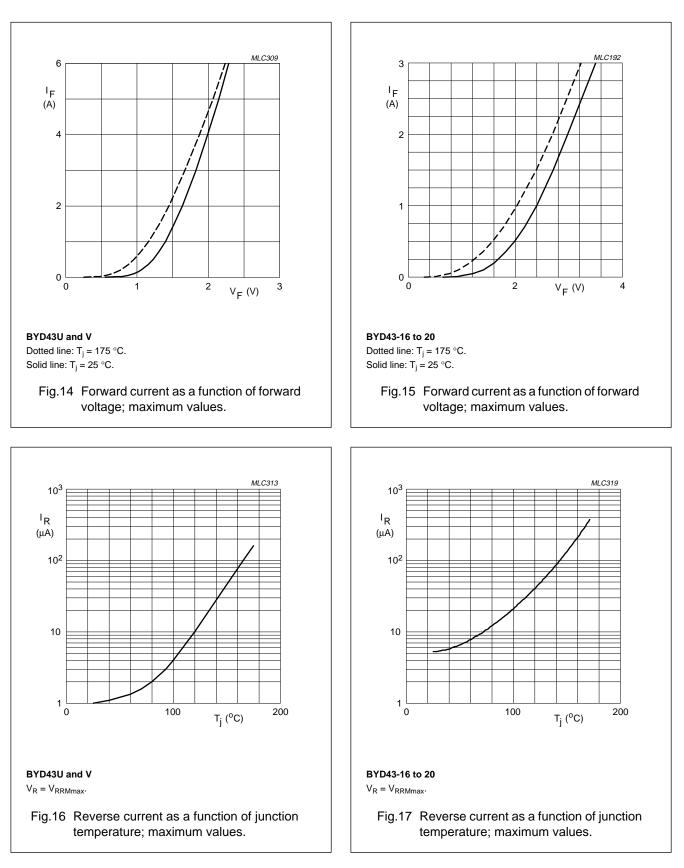


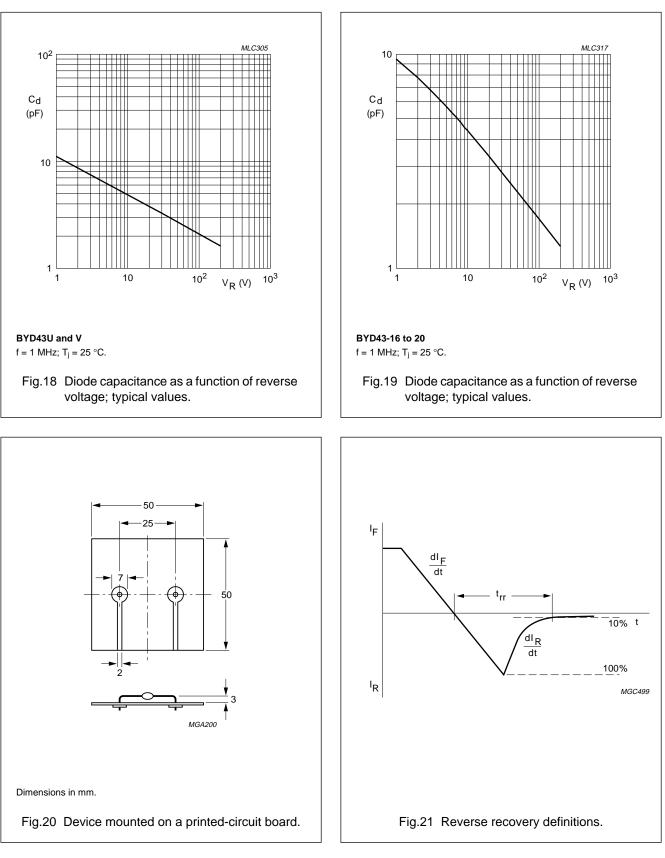
#### BYD43-16 to 20

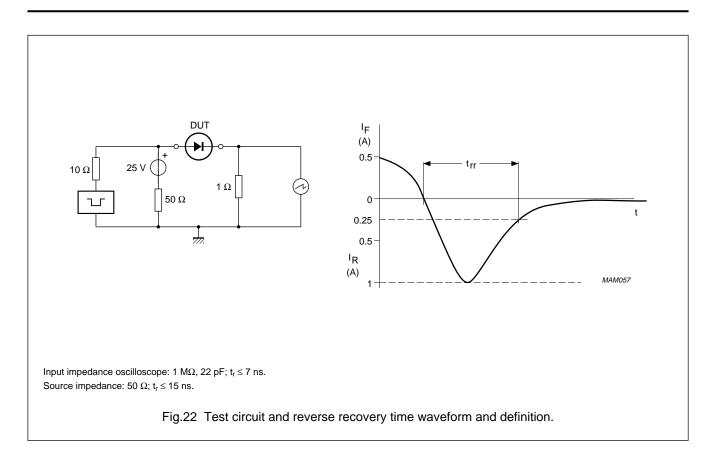
a =  $I_{F(RMS)}/I_{F(AV)}$ ;  $V_R = V_{RRMmax}$ ;  $\delta = 0.5$ .

Fig.11 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.



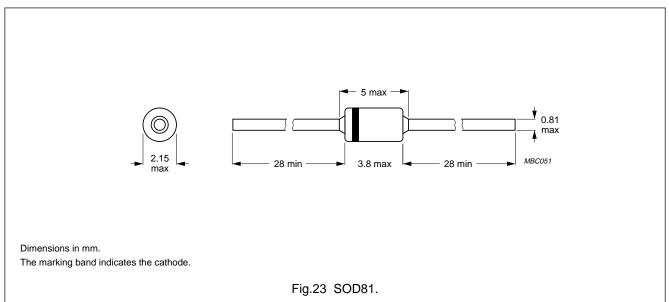






## **BYD43** series

#### PACKAGE OUTLINE



#### DEFINITIONS

Data Sheet Status			
Objective specification	This data sheet contains target or goal specifications for product development.		
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.		
Product specification	This data sheet contains final product specifications.		
Limiting values			
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.			
Application information			
Where application information is given, it is advisory and does not form part of the specification.			

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.